

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Takashi Sakai	12/04/2009
RECEIVING PARTY DATA	
Name:	Sumco Corporation
Street Address:	2-1, Shibaura 1-chome
City:	Minato-ku, Tokyo
State/Country:	JAPAN
Postal Code:	105-8634
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12644312
CORRESPONDENCE DATA	
Fax Number:	(206)224-0779
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	(206)682-8100
Email:	efiling@cojk.com
Correspondent Name:	Laura A. Cruz, Esq.
Address Line 1:	Christensen O'Connor Johnson Kindness
Address Line 2:	1420 Fifth Avenue, Suite 2800
Address Line 4:	Seattle, WASHINGTON 98101-2347
ATTORNEY DOCKET NUMBER:	SGIP134203
NAME OF SUBMITTER:	Laura A. Cruz
Total Attachments: 1 source=34203_Assignment#page1.tif	

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PATENT
 REEL: 023789 FRAME: 0797

ASSIGNMENT

WHEREAS, I/we, the inventor(s) whose name(s) and residence address(es) appear(s) below, am/are the sole/joint inventor(s) named in an application for Letters Patent of the United States, entitled METHOD OF PRODUCING BONDED SILICON WAFER, filed herewith or as Application Serial No. 12/644312 on December 22, 2009 (I/we hereby authorize my/our attorneys of the firm of Christensen O'Connor Johnson Kindness^{PLLC}, 1420 Fifth Avenue, Suite 2800, Seattle, Washington 98101, to insert the application number of said application);

AND, WHEREAS, SUMCO CORPORATION, a corporation of Japan having a principal place of business at 2-1, Shibaura 1-chome, Minato-ku, Tokyo 105-8634, Japan (hereinafter referred to as ASSIGNEE), is desirous of acquiring my/our entire right and title to and interest in my/our invention(s) disclosed in said application;

NOW, THEREFORE, for sufficient, good and valuable consideration, the receipt of which is hereby acknowledged, I/we do hereby sell, assign and transfer unto ASSIGNEE my/our entire right and title to and interest in said application and said invention(s), including the right to apply for international patents and patents thereon in foreign countries in my/our name(s) or in the name of ASSIGNEE, and including the right to apply for any continuation, division, extension, reissue, or reexamination of all applications and patents on said invention(s) in my/our name(s) or in the name of ASSIGNEE, said invention(s) and all applications and patents on said invention(s) to be held and enjoyed by ASSIGNEE as entirely as the same would have been held and enjoyed by me/us had this sale, assignment and transfer not been made; and I/we do hereby further agree and promise to execute all instruments and render all such assistance as ASSIGNEE may request in order to make and prosecute any and all applications on said invention(s), to enforce any and all patents on said invention(s), and to confirm in ASSIGNEE legal title to said invention(s) and all applications and patents on said invention(s), all without charge to ASSIGNEE but at no expense to me/us.

Executed at Tokyo Japan (city), Japan, this 4th day of December, 2009.

Takashi SAKAI

Name: Takashi SAKAI

c/o SUMCO CORPORATION, 2-1,
Shibaura 1-chome, Minato-ku, Tokyo
105-8634, Japan

Residence Address

Witness:

Akenko Suzuki